

MT18Ex

- MicroThin為附18 μ m載體銅箔的超薄銅箔。
MicroThin is ultra thin foil with 18 μ m carrier foil.
- 最適用於線寬/線距(L/ S) =20/20~35/35之應用。
Usable for fine pitch pattern L/S=20/20 – 35/35 formation.
- 與MT18SD-H相比較, 其更低的粗糙度更適用於極細線路之應用。
Lower profile compare with MT18SD-H, more suitable for very fine pattern.

用途/Application

- IC封裝載板
/Semiconductor Package
- 高密度互連技術板
/High Density Interconnect

構成/Composition



生產地點/Production Site

- 日本 / Japan
- 馬來西亞/Malaysia

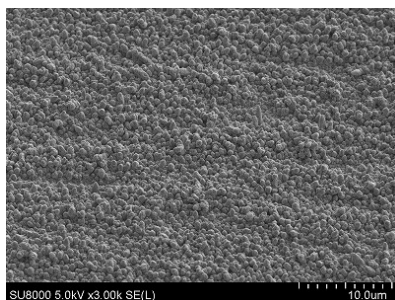
代表性特性數據/Representative

	μ m	Area weight (g/m ²)	Laminate side Rz(μ m)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
MT18Ex	1.5	20	2	—	—	1.2
	2	24	2	—	—	1.2
	3	33	2	—	—	1.2
	5	51	2	—	—	1.2

※上述表列為代表性數據非保證值
This is representative data, not guaranteed.

※Peel Strength為增鍍到35 μ m厚度之後的測試值
Evaluated after plated up to 35 μ m.

處理面/Laminate side



阻劑面/ resist side

